

## FEATURES

- Member of the Texas Instruments Widebus™ Family
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Sub-1-V Operable
- Max  $t_{pd}$  of 2 ns at 1.8 V
- Low Power Consumption, 20- $\mu$ A Max  $I_{CC}$
- $\pm 8$ -mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## DESCRIPTION/ORDERING INFORMATION

This 16-bit buffer/driver is operational at 0.8-V to 2.7-V  $V_{CC}$ , but is designed specifically for 1.65-V to 1.95-V  $V_{CC}$  operation.

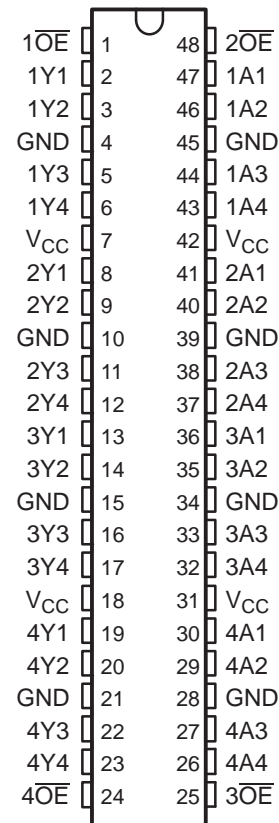
The SN74AUC16244 is designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. It provides true outputs and symmetrical active-low output-enable ( $\overline{OE}$ ) inputs.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

DGG OR DGV PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40C to 85C	TSSOP – DGG	Tape and reel	SN74AUC16244DGGR	AUC16244
	TVSOP – DGV	Tape and reel	SN74AUC16244DGVR	MH244
	VFBGA – GQL	Tape and reel	SN74AUC16244GQLR	MH244

(1) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).



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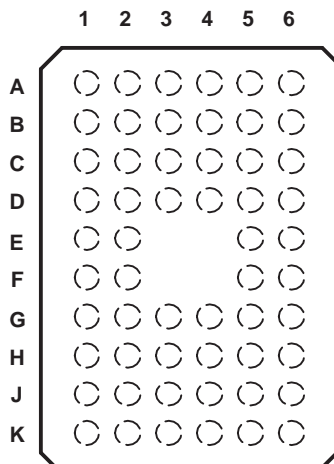
# SN74AUC16244

## 16-BIT BUFFER/DRIVER

### WITH 3-STATE OUTPUTS

SCES399E—JULY 2002—REVISED FEBRUARY 2008

#### GQL PACKAGE (TOP VIEW)



#### TERMINAL ASSIGNMENTS<sup>(1)</sup>

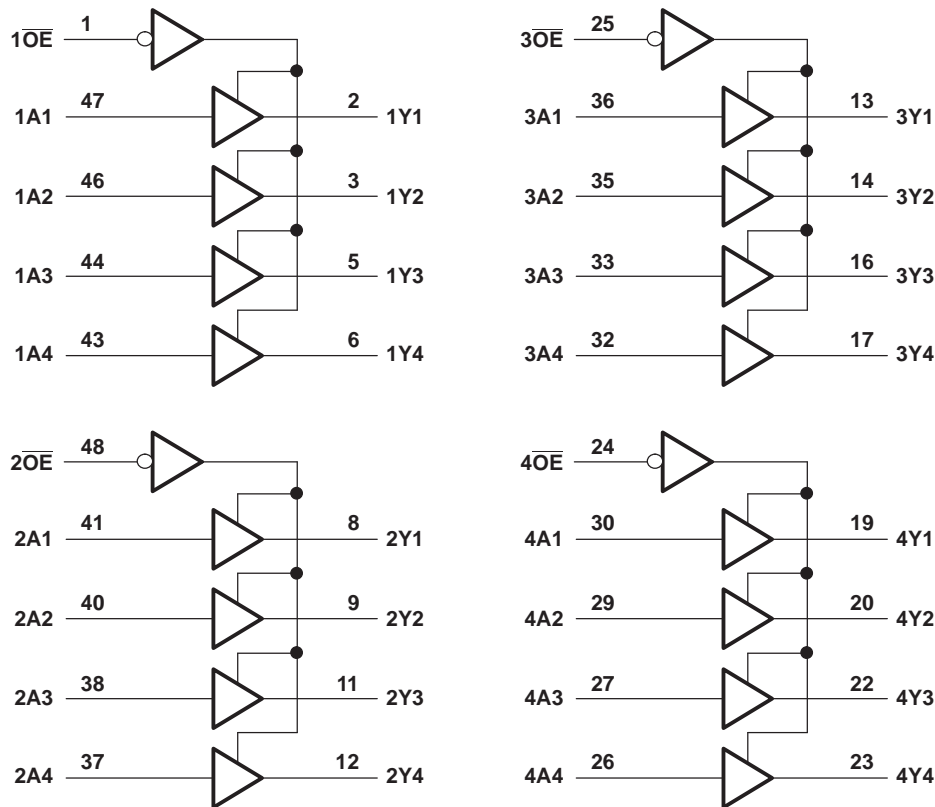
	1	2	3	4	5	6
<b>A</b>	$\overline{1OE}$	NC	NC	NC	NC	$\overline{2OE}$
<b>B</b>	1Y2	1Y1	GND	GND	1A1	1A2
<b>C</b>	1Y4	1Y3	$V_{CC}$	$V_{CC}$	1A3	1A4
<b>D</b>	2Y2	2Y1	GND	GND	2A1	2A2
<b>E</b>	2Y4	2Y3			2A3	2A4
<b>F</b>	3Y1	3Y2			3A2	3A1
<b>G</b>	3Y3	3Y4	GND	GND	3A4	3A3
<b>H</b>	4Y1	4Y2	$V_{CC}$	$V_{CC}$	4A2	4A1
<b>J</b>	4Y3	4Y4	GND	GND	4A4	4A3
<b>K</b>	$\overline{4OE}$	NC	NC	NC	NC	$\overline{3OE}$

(1) NC - No internal connection

#### FUNCTION TABLE (EACH 4-BIT BUFFER)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

**LOGIC DIAGRAM (POSITIVE LOGIC)**



Pin numbers shown are for the DGG and DGV packages.

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
$V_{CC}$	Supply voltage range	-0.5	3.6	V	
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	3.6	V	
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	-0.5	3.6	V	
$V_O$	Output voltage range <sup>(2)</sup>	-0.5	$V_{CC} + 0.5$	V	
$I_{IK}$	Input clamp current	$V_I < 0$		-50	mA
$I_{OK}$	Output clamp current	$V_O < 0$		-50	mA
$I_O$	Continuous output current			20	mA
	Continuous current through $V_{CC}$ or GND			100	mA
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	DGG package		70	C/W
		DGV package		58	
		GQL package		42	
$T_{stg}$	Storage temperature range	-65	150	C	

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

**SN74AUC16244**  
**16-BIT BUFFER/DRIVER**  
**WITH 3-STATE OUTPUTS**

SCES399E–JULY 2002–REVISED FEBRUARY 2008

**RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>**

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	0.8	2.7	V
$V_{IH}$	High-level input voltage	$V_{CC} = 0.8\text{ V}$	$V_{CC}$	V
		$V_{CC} = 1.1\text{ V to }1.95\text{ V}$	$0.65 \cdot V_{CC}$	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7	
$V_{IL}$	Low-level input voltage	$V_{CC} = 0.8\text{ V}$	0	V
		$V_{CC} = 1.1\text{ V to }1.95\text{ V}$	$0.35 \cdot V_{CC}$	
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	0.7	
$V_I$	Input voltage	0	3.6	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 0.8\text{ V}$	-0.7	mA
		$V_{CC} = 1.1\text{ V}$	-3	
		$V_{CC} = 1.4\text{ V}$	-5	
		$V_{CC} = 1.65\text{ V}$	-8	
		$V_{CC} = 2.3\text{ V}$	-9	
$I_{OL}$	Low-level output current	$V_{CC} = 0.8\text{ V}$	0.7	mA
		$V_{CC} = 1.1\text{ V}$	3	
		$V_{CC} = 1.4\text{ V}$	5	
		$V_{CC} = 1.65\text{ V}$	8	
		$V_{CC} = 2.3\text{ V}$	9	
$\Delta t/\Delta v$	Input transition rise or fall rate		20	ns/V
$T_A$	Operating free-air temperature	-40	85	C

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>		I <sub>OH</sub> = -100 μA	0.8 V to 2.7 V	V <sub>CC</sub> - 0.1			V
		I <sub>OH</sub> = -0.7 mA	0.8 V	0.55			
		I <sub>OH</sub> = -3 mA	1.1 V	0.8			
		I <sub>OH</sub> = -5 mA	1.4 V	1			
		I <sub>OH</sub> = -8 mA	1.65 V	1.2			
		I <sub>OH</sub> = -9 mA	2.3 V	1.8			
V <sub>OL</sub>		I <sub>OL</sub> = 100 μA	0.8 V to 2.7 V			0.2	V
		I <sub>OL</sub> = 0.7 mA	0.8 V	0.25			
		I <sub>OL</sub> = 3 mA	1.1 V			0.3	
		I <sub>OL</sub> = 5 mA	1.4 V			0.4	
		I <sub>OL</sub> = 8 mA	1.65 V			0.45	
		I <sub>OL</sub> = 9 mA	2.3 V			0.6	
I <sub>I</sub>	A or $\overline{OE}$ inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	0 to 2.7 V			5	μA
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 2.7 V	0			10	μA
I <sub>OZ</sub>		V <sub>O</sub> = V <sub>CC</sub> or GND	2.7 V			10	μA
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	0.8 V to 2.7 V			20	μA
C <sub>i</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	2.5 V	3.5		4.5	pF
C <sub>o</sub>		V <sub>O</sub> = V <sub>CC</sub> or GND	2.5 V	6		7.5	pF

(1) All typical values are at T<sub>A</sub> = 25C.

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

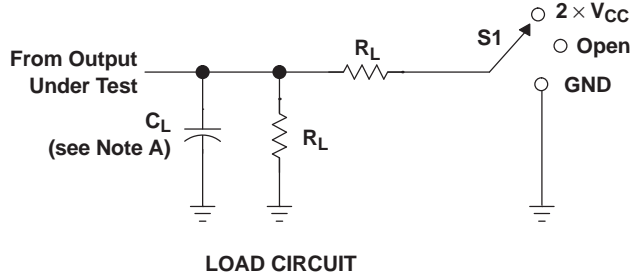
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 0.8 V		V <sub>CC</sub> = 1.2 V 0.1 V		V <sub>CC</sub> = 1.5 V 0.1 V		V <sub>CC</sub> = 1.8 V 0.15 V			V <sub>CC</sub> = 2.5 V 0.2 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX		
t <sub>pd</sub>	A	Y	5.4	0.8	2.8	0.6	1.9	0.7	1.3	1.8	0.5	1.8	ns	
t <sub>en</sub>	$\overline{OE}$	Y	8	1	4.4	0.7	2.6	0.8	1.4	2.5	0.6	1.9	ns	
t <sub>dis</sub>	$\overline{OE}$	Y	12	1.9	4.9	1	4.6	1.5	2.6	4	0.5	2	ns	

## OPERATING CHARACTERISTICS

T<sub>A</sub> = 25C

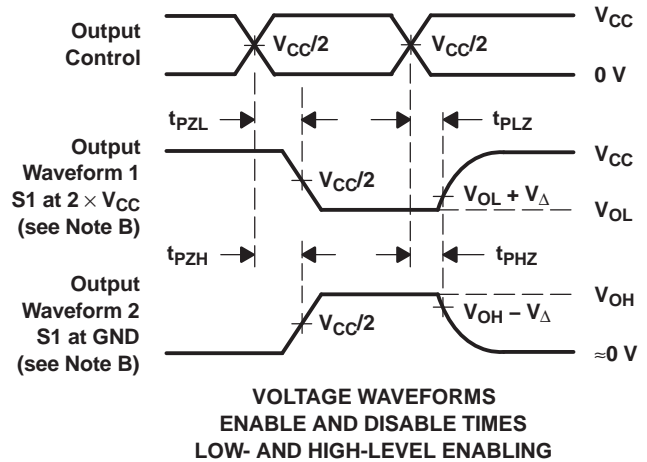
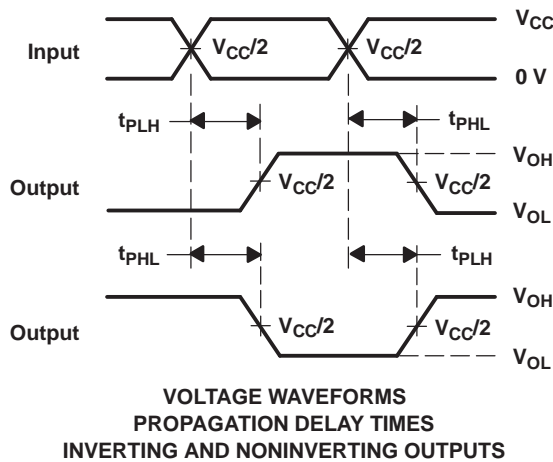
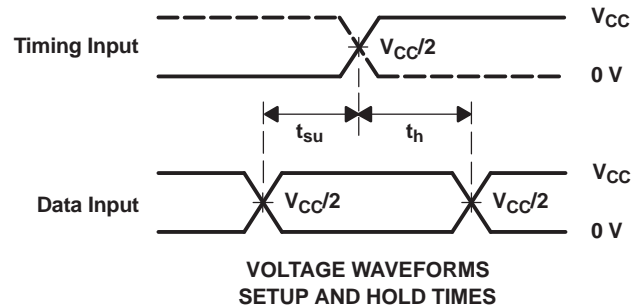
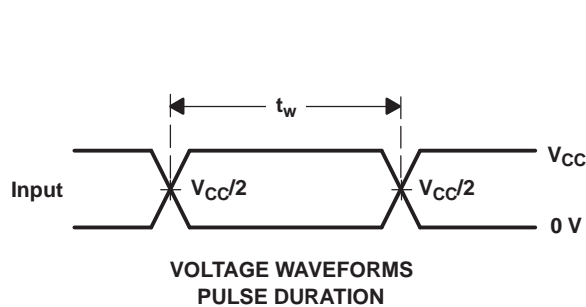
PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 0.8 V	V <sub>CC</sub> = 1.2 V	V <sub>CC</sub> = 1.5 V	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	UNIT
			TYP	TYP	TYP	TYP	TYP	
C <sub>pd</sub>	Power dissipation capacitance	Outputs enabled f = 10 MHz	21	22	23	25	30	pF
			1	1	1	1	1	

**PARAMETER MEASUREMENT INFORMATION**



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	$C_L$	$R_L$	$V_{\Delta}$
0.8 V	15 pF	2 k $\Omega$	0.1 V
1.2 V $\pm$ 0.1 V	15 pF	2 k $\Omega$	0.1 V
1.5 V $\pm$ 0.1 V	15 pF	2 k $\Omega$	0.1 V
1.8 V $\pm$ 0.15 V	30 pF	1 k $\Omega$	0.15 V
2.5 V $\pm$ 0.2 V	30 pF	500 $\Omega$	0.15 V



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ , slew rate  $\geq$  1 V/ns.  
D. The outputs are measured one at a time, with one transition per measurement.  
E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
H. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AUC16244DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AUC16244	<a href="#">Samples</a>
SN74AUC16244DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	MH244	<a href="#">Samples</a>
SN74AUC16244GQLR	OBSOLETE	BGA MICROSTAR JUNIOR	GQL	56		TBD	Call TI	Call TI	-40 to 85		
SN74AUC16244ZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	MH244	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUC16244DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74AUC16244DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74AUC16244ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1

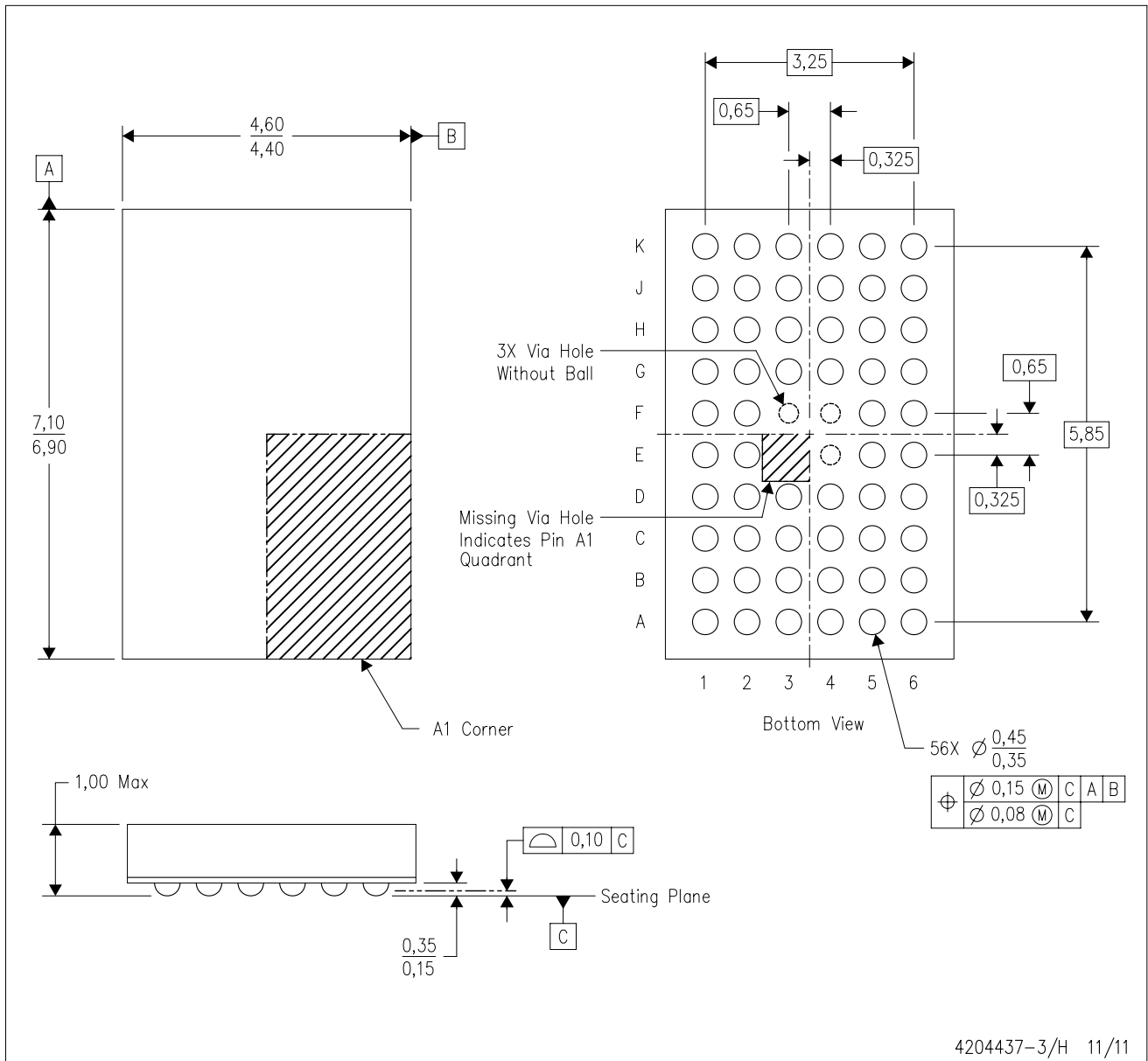
**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUC16244DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74AUC16244DGVR	TVSOP	DGV	48	2000	367.0	367.0	38.0
SN74AUC16244ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	333.2	345.9	28.6

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



4204437-3/H 11/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-285 variation BA-2.
  - D. This package is Pb-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



4073251/E 08/00

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-285 variation BA-2.
  - D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
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